

Title (en)  
DIABETIC, BRAN-FREE FLOUR FOR THE PRODUCTION OF BAKING INDUSTRY PRODUCTS, ESPECIALLY BREAD, PASTRIES AND CAKES

Title (de)  
DIABETISCHES KLEIEFREIES MEHL ZUR HERSTELLUNG VON BÄCKEREIERZEUGNISSEN, INSBESONDERE BROT, KONFITOREIWAREN UND KUCHEN

Title (fr)  
FARINE SANS SON POUR DIABETIQUES DESTINEE A LA FABRICATION DE PRODUITS DE BOULANGERIE ET NOTAMMENT DE PAIN, D'ARTICLES DE PATISserie ET DE GATEAUX

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Application  
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Abstract (en)  
[origin: WO03086083A1] The invention relates to bran-free diabetic flour or flour mixture for the production of baking industry products, especially bread, pastries, cakes characterised by that it contains 30-80 m% wheat flour, 15-40 m% gluten flour, 2-10 m% guar flour and advantageously 5-15 m% rye flour, as well as known baking industry taste, aroma, state improver and other additives. Procedure for the production of bran-free diabetic baking industry product, especially bread, pastries and cakes characterised by that the flour mixture or flour according to claim 1, water and known leavening additive material when required are made into products using known baking industry procedures. Additional subject of the invention is an additive mixture for the production of bran-free diabetic baking industry products, especially bread, pastries, cakes characterised by that the additive mixture contains 20-60 m% gluten flour, 4-30 m% guar flour and advantageously 525 m% rye flour, as well as known baking industry taste, aroma, stabiliser and other additives as required. Procedure for the production of bran-free diabetic baking industry products, especially bread, pastries, cakes characterised by that the additive mixture according to claim 3 is added to usual baking industry basic materials, and the finished product is made using known baking industry procedures.

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